

Title: MULTI-STEP DRY ETCHING METHOD
FOR SOI WAFER

Inventor(s): Michihiko YANAGISAWA et al.

Application No.: New Application

Docket No.: 506212001200

FIG. 1

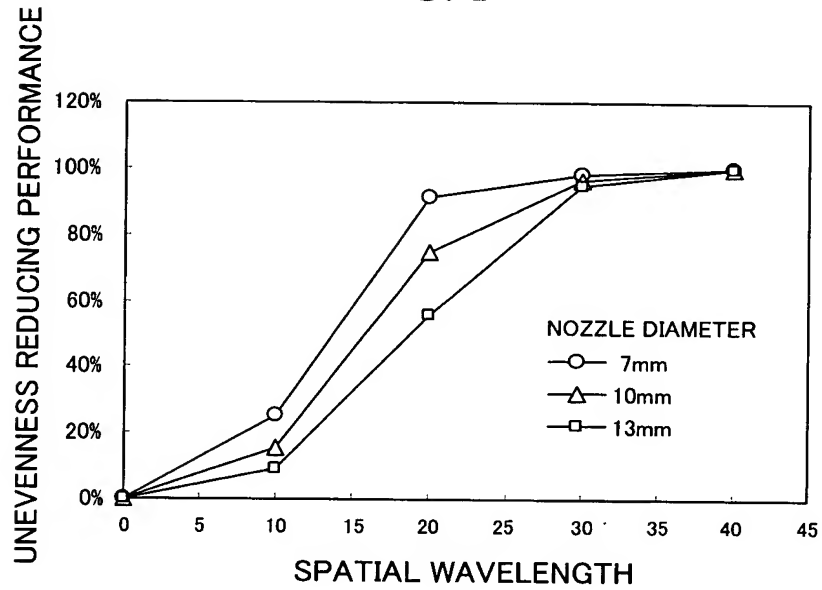
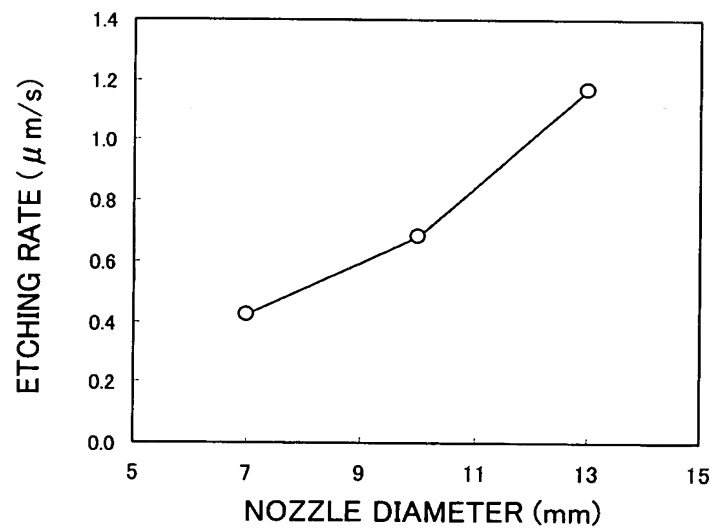
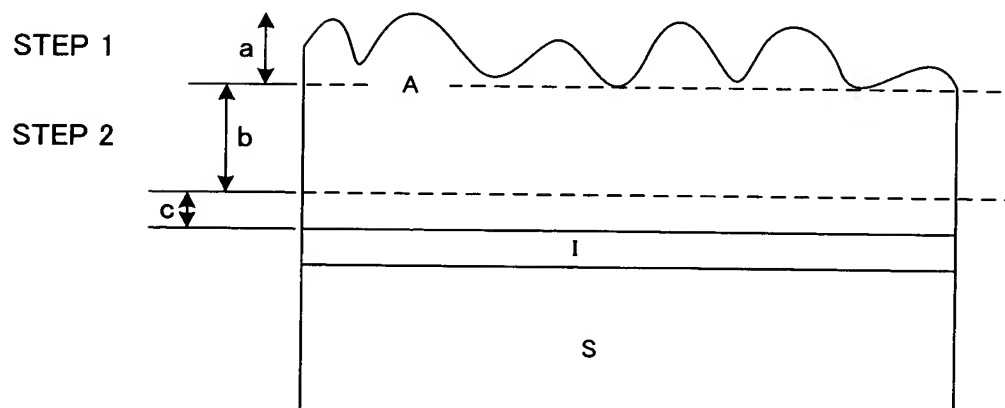


FIG. 2





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FIG. 5

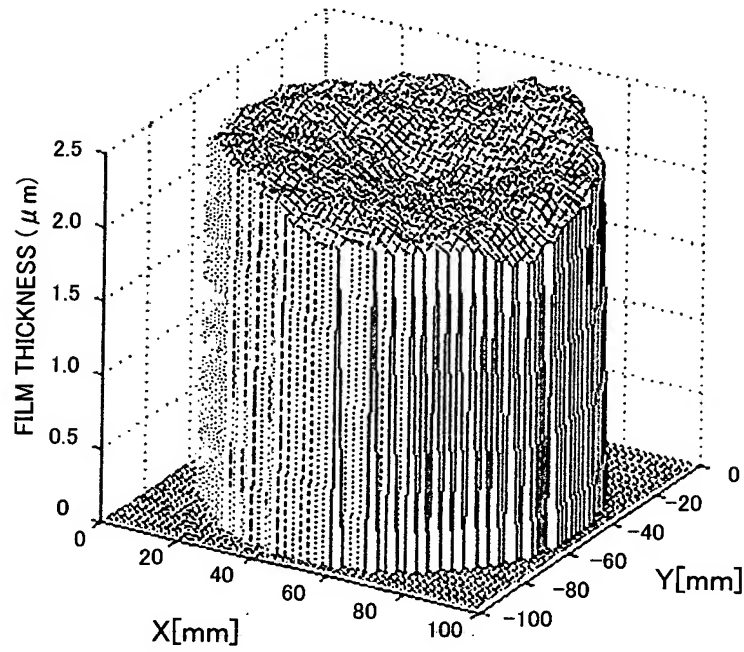
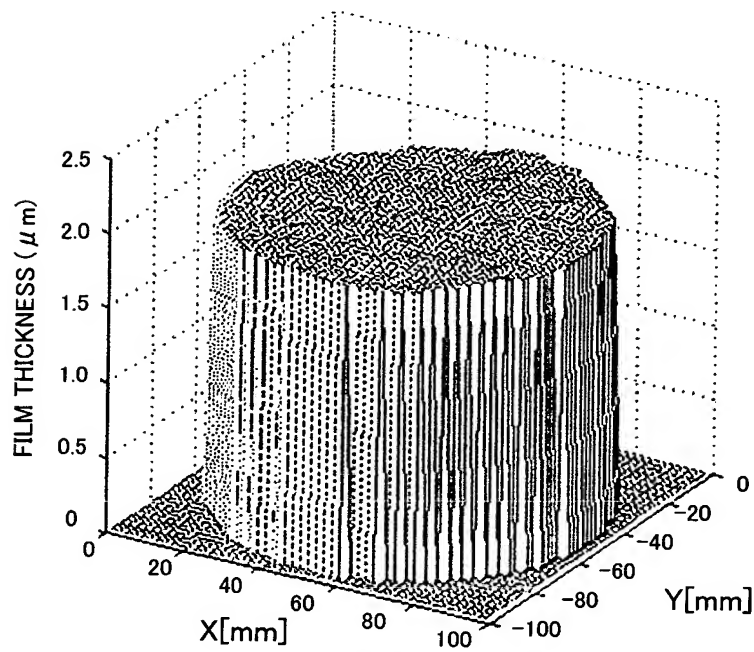


FIG. 6



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FIG. 7

